#1IDS 1614

PTO/SB/08a/b (08-03)
Approved for use through 07/31/2006. OMB 0651-0031
U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE
Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

| Sub   | Substitute for form 1449A/B/PTO |         |            | Complete if Known      |                   |  |
|-------|---------------------------------|---------|------------|------------------------|-------------------|--|
| 000   | 550010101101111114401401        | . •     |            | Application Number     | NOT YET ASSIGNED  |  |
| 11    | NFORMATIO                       | N DI    | SCLOSURE   | Filing Date            | January 6, 2004   |  |
| S     | TATEMENT                        | BY /    | APPLICANT  | First Named Inventor   | Hongmei Wang      |  |
| _     |                                 |         |            | Art Unit               | N/A               |  |
|       | (Use as many si                 | eets as | necessary) | Examiner Name          | Not Yet Assigned  |  |
| Sheet | 1                               | of      | 1          | Attorney Docket Number | M4065.0536/P536-B |  |

| U.S. PATENT DOCUMENTS |              |   |                                |  |   |
|-----------------------|--------------|---|--------------------------------|--|---|
| Examiner              | Cite<br>No.1 | Document Number                           | Publication Date<br>MM-DD-YYYY | Name of Patentee or<br>Applicant of Cited Document | Pages, Columns, Lines, Where<br>Relevant Passages or Relevant<br>Figures Appear |
| Initials*             |              | Number-Kind Code <sup>2</sup> ( if known) |                                |  |   |
| MY                    | AA           | 5,340,759                                 | 08-1994                        | Hsieh et al.*                                      |   |
| 1                     | AB           | 6,277,675                                 | 08-2001                        | Tung*  |   |
| $\neg$                | AC           | 6,288,949                                 | 09-2001                        | Hidaka et al.*                                     |   |
|                       | AD           | 6,331,458                                 | 12-2001                        | Anjum et al.*                                      |   |
|                       | AE           | 6,339,244                                 | 01-2002                        | Krivokapic*  |   |
|                       | AF           | 6,424,016                                 | 07-23-2002                     | Houston*   |   |
|                       | AG           | 6,424,009                                 | 07-23-2002                     | Dong-Hyuk Ju*                                      |   |
| V                     | АН           | 6,552,401                                 | 04-22-2003                     | Dennison*  |   |
| MIST                  | Al           | 6,294,817                                 | 09-2001                        | Srinivasan et al.*                                 |   |

|                       |              | FOREI  | GN PATENT                         | DOCUMENTS  |   |    |
|-----------------------|--------------|--|-----------------------------------|--|---|----|
| Examiner<br>Initials* | Cite<br>No.1 | Foreign Patent Document  Country Code <sup>3</sup> -Number <sup>4</sup> -Kind Code <sup>6</sup> (If known) | Publication<br>Date<br>MM-DD-YYYY | Name of Patentee or<br>Applicant of Cited Document | Pages, Columns, Lines,<br>Where Relevant Passages<br>or Relevant Figures Appear | τ° |
|                       |              |  |                                   |  |   |    |

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. Applicant's unique citation designation number (optional). See Kinds Codes of USPTO Patent Documents at <a href="https://www.uspto.gov">www.uspto.gov</a> or MPEP 901.04. Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. Applicant is to place a check mark here if English language Translation is attached.

| NON PATENT LITERATURE DOCUMENTS |              |   |            |  |  |
|---------------------------------|--------------|---|------------|--|--|
|                                 | Cite<br>No.1 | Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published. | <b>T</b> 2 |  |  |
| MY                              | CA           | S.M. Sze, "Physics of Semiconductor Devices," John Wiley & Sons, New York, (1981), pp. 454-455.*  |            |  |  |
|                                 | СВ           | Syd R. Wilson, et al., "Handbook of Multilevel Metallization for Integrated Circuits," Noyes Publ., Westwood, New Jersey, (1993), pp. 259-264.*   |            |  |  |
| V                               | СС           | Gary E. McGuire, "Semiconductor Materials and Process Technology Handbook," Noyes Publ., Norwich, New York, (1988), pp. 46-47.*   |            |  |  |
| MK                              | CD           | Julian J. Sanchez, et al., "Drain-Engineered Hot-Electron-Resistant Device Structures: A Review," IEEE Trans. On Electron Devices, Vol. 36, No. 6, (1989), pp. 1125-1132.*  |            |  |  |

<sup>\*</sup>EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

| Examiner Signature March Signature | Date 3//5/2005 |
|------------------------------------|----------------|
|                                    | 7 7            |

Applicant's unique citation designation number (optional). Applicant is to place a check mark here if English language Translation is attached.